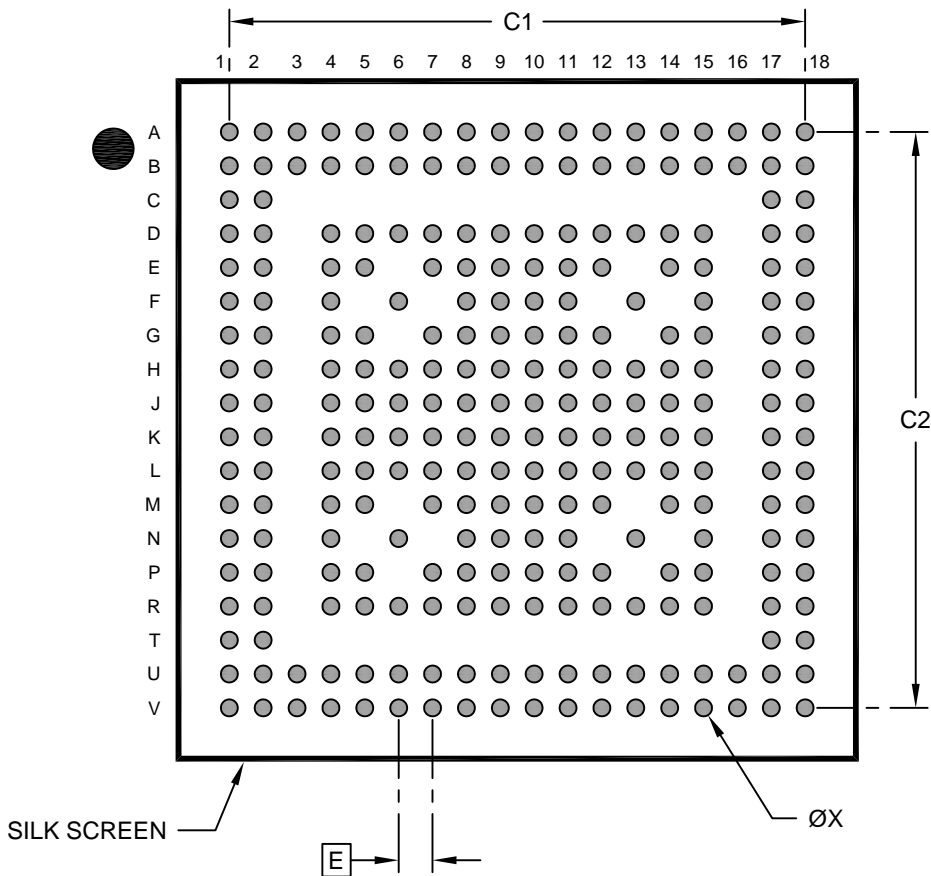


# 256-Ball Thin Fine Pitch Ball Grid Array (AYB) - 8x8x1.05 mm Body [TFBGA]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E			0.40 BSC	
Contact Pad Spacing	C1			6.80	
Contact Pad Spacing	C2			6.80	
Contact Pad Diameter (X256)	X				0.20

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.